REPLACEMENT SHEET

- 6 NOV 2002

162162

SEMICONDUCTOR WAFER DIVIDING METHOD

Abstract of the Disclosure

A semiconductor wafer (4), on whose face side many rectangular areas are demarcated by streets (14) arranged in a lattice fashion where the rectangular areas are semiconductor chips, is divided into the chips by forming a resist (20) on the face side of the semiconductor wafer (4), then physically removing the resist (20) in areas extending along the streets (14) and etching the semiconductor wafer along the streets (14). Preferably the physical removal step involves cutting the resist (20) along the streets (14) using a dicer.

Figure 4

G00002